Layer stackup and fabrication

Source project settings. Dimensions and fabrication parameters come from the saved PCB.

Layer	Type	Material	mm
F.SilkS	Top Silk Screen	—	—
F.Paste	Top Solder Paste	—	—
F.Mask	Top Solder Mask	—	0.01
F.Cu	copper	—	0.035
dielectric 1	prepreg	FR4	0.1
In1.Cu	copper	—	0.035
dielectric 2	core	FR4	0.535
In2.Cu	copper	—	0.035
dielectric 3	prepreg	FR4	0.1
In3.Cu	copper	—	0.035
dielectric 4	core	FR4	0.535
In4.Cu	copper	—	0.035
dielectric 5	prepreg	FR4	0.1
B.Cu	copper	—	0.035
B.Mask	Bottom Solder Mask	—	0.01
B.Paste	Bottom Solder Paste	—	—
B.SilkS	Bottom Silk Screen	—	—

Saved board parameters

Property	Saved value
Outline	145.93 × 98.25 mm
Board thickness	1.6 mm
Copper layers	6
Footprints	180
Track/arc items	3875
Vias	782

Saved routing rules / mm

Class	Clearance	Track	Via/drill
Default	0.15	0.1	0.3/0.15
Data	0.15	0.12	0.3/0.15
Power	0.15	0.3	0.3/0.15

These drawings record the source design. Confirm material, layer stack and fabrication capabilities against the native project before manufacture.

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Units: mm. Source CAD governs. Regenerate after design changes.